

IPB80P03P4L-04-VB Datasheet P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)	
- 30	0.005 at V _{GS} = - 10 V - 100	60nC		
- 30	0.006 at $V_{GS} = -4.5 \text{ V}$	- 85	OOTIC	

FEATURES

- · Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

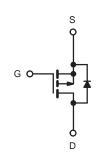


RoHS

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch





P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		- 100		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 85		
Continuous Diam Curient (1) = 130 °C)	T _A = 25 °C	l _D	-68 ^{a, b}		
	T _A = 70 °C		-56 ^{a, b}		
Pulsed Drain Current		I _{DM}	- 260	Α	
Continuous Course Drain Diade Current	T _C = 25 °C		- 4.8		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.5 ^{a, b}		
Avalanche Current	1 0411	I _{AS}	- 80		
Single-Pulse Avalanche Energy L = 0.1 mH		E _{AS}	280	mJ	
	T _C = 25 °C		254		
Maximum Power Dissipation	T _C = 70 °C		225	10/	
	T _A = 25 °C	P _D	4.0 ^{a, b}	W	
	T _A = 70 °C		2.8 ^{a, b}		
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$ $I_D = -250 \mu A$			- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	η = - 230 μΑ		-5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.0		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA	
Zara Cata Valtaga Dusin Comment	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V			- 1	μА	
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 10 A		0.005		Ω	
Drain-Source On-State Resistance ^a		V _{GS} = - 4.5 V, I _D = - 8 A		0.006			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 10 A		28		S	
Dynamic ^b							
Input Capacitance	C _{iss}			4850		pF	
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		1560			
Reverse Transfer Capacitance	C _{rss}			640			
T. 10 (0)		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -10 \text{ A}$		115		20	
Total Gate Charge	Q _g			56			
Gate-Source Charge	Q_{gs} $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -10 \text{ A}$		8		nC		
Gate-Drain Charge	Q _{gd}			22		1	
Gate Resistance	R _g	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		40	70		
Fall Time	t _f			9	18		
Turn-On Delay Time t _{d(on)}				48	80	ns	
Rise Time				92	160		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		34	60		
Fall Time	t _f			19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.6	- A	
Pulse Diode Forward Current	I _{SM}				- 65		
Body Diode Voltage	V_{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time t _{rr}				27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 10 A dl/dt 100 A/:- T 0500		16	27	nC	
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12			
Reverse Recovery Rise Time	t _b]		15		ns	

Notes:

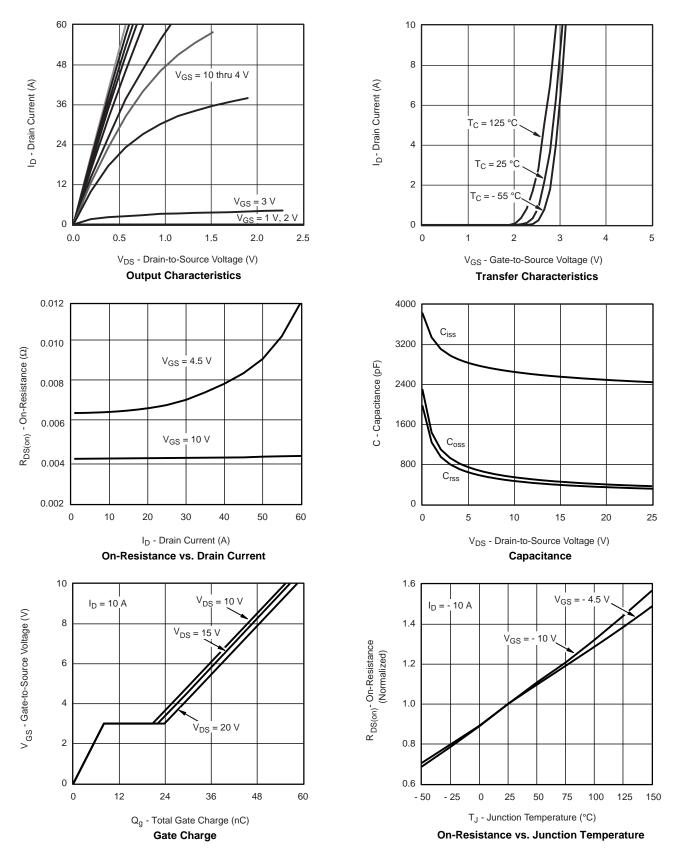
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

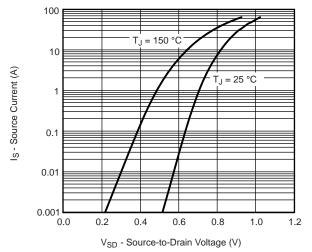


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

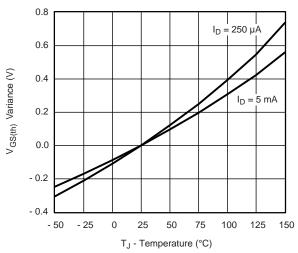




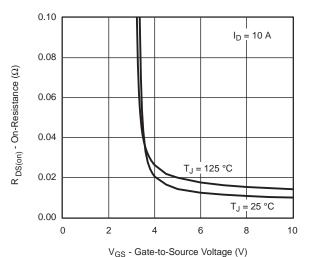
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



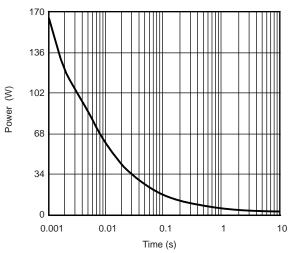
Source-Drain Diode Forward Voltage



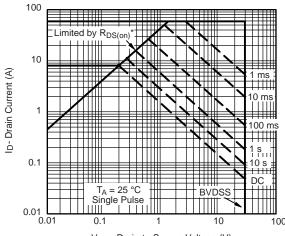
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

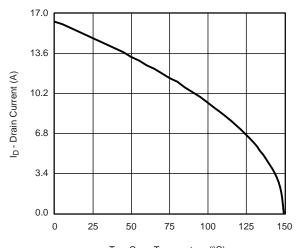


 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

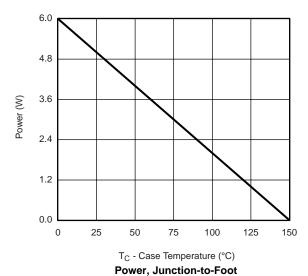


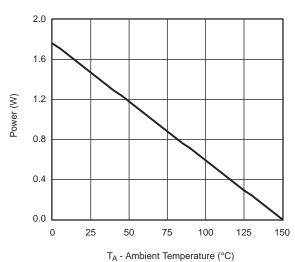
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



 $T_{\mbox{\scriptsize C}}$ - Case Temperature (°C)







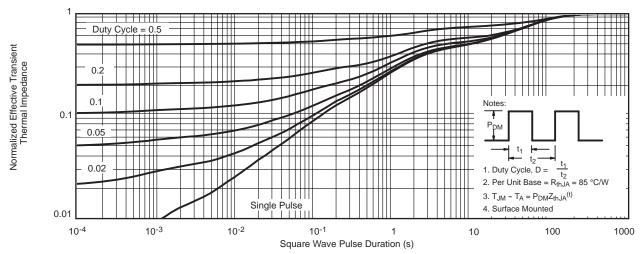
Power Derating, Junction-to-Ambient

服务热线:400-655-8788

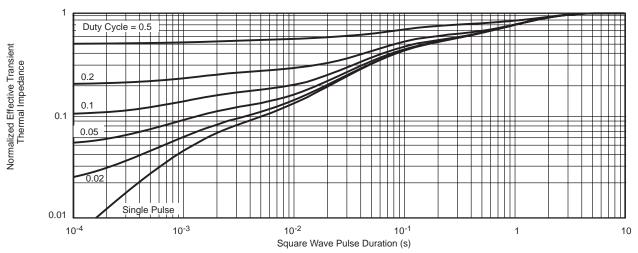
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

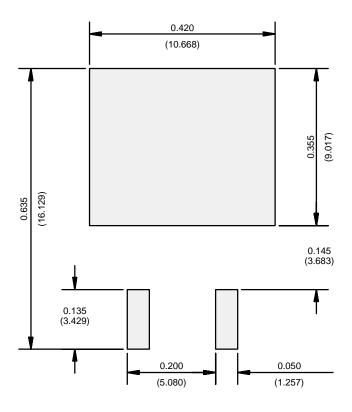


Normalized Thermal Transient Impedance, Junction-to-Foot



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RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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